TOSHIBA Field-Effect Transistor Silicon N / P Channel MOS Type

SSM6L35FE

- High-Speed Switching Applications
- Analog Switch Applications
- N-ch: 1.2-V drive P-ch: 1.2-V drive
- N-ch, P-ch, 2-in-1
- Low ON-resistance Q1 N-ch: $R_{on} = 20 \Omega (max) (@V_{GS} = 1.2 V)$

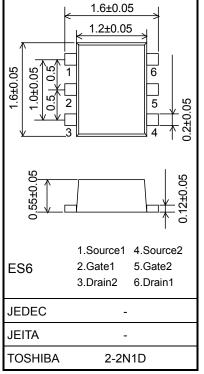
: $R_{on} = 8 \Omega (max) (@V_{GS} = 1.5 V)$: $R_{on} = 4 \Omega (max) (@V_{GS} = 2.5 V)$

: $R_{on} = 3 \Omega (max) (@V_{GS} = 4.0 V)$

- Q2 P-ch: R_{on} = 44 Ω (max) (@V_{GS} = -1.2 V)
 - : R_{on} = 22 Ω (max) (@V_{GS} = -1.5 V)
 - : R_{on} = 11 Ω (max) (@V_{GS} = -2.5 V)
 - : R_{on} = 8 Ω (max) (@V_{GS} = -4.0 V)

Q1 Absolute Maximum Ratings (Ta = 25°C)

Characteristics		Symbol	Rating	Unit	
Drain-source voltage		V _{DSS}	20	V	
Gate-source voltage		V _{GSS}	±10	V	
Drain current	DC	۱ _D	180		
	Pulse	I _{DP}	360	mA	



Weight: 3.0 mg (typ.)

Q2 Absolute Maximum Ratings (Ta = 25°C)

Characteristics		Symbol	Rating	Unit
Drain-source voltage		V _{DSS}	-20	V
Gate-source voltage		V _{GSS}	±10	V
Drain current	DC	۱ _D	-100	mA
	Pulse	I _{DP}	-200	ША

Absolute Maximum Ratings (Ta = 25 °C) (Common to the Q1, Q2)

Characteristic	Symbol	Rating	Unit	
Drain power dissipation	P _D (Note 1)	150	mW	
Channel temperature	T _{ch}	150	°C	
Storage temperature range	T _{stg}	-55 to 150	°C	

Note: Using continuously under heavy loads (e.g. the application of high temperature/current/voltage and the significant change in temperature, etc.) may cause this product to decrease in the reliability significantly even if the operating conditions (i.e. operating temperature/current/voltage, etc.) are within the absolute maximum ratings.

Please design the appropriate reliability upon reviewing the Toshiba Semiconductor Reliability Handbook ("Handling Precautions"/"Derating Concept and Methods") and individual reliability data (i.e. reliability test report and estimated failure rate, etc).

Note 1: Total rating

Mounted on an FR4 board

 $(25.4 \text{ mm} \times 25.4 \text{ mm} \times 1.6 \text{ mm}, \text{Cu Pad: } 0.135 \text{ mm}^2 \times 6)$

Start of commercial production 2008-03

Unit: mm

Q1 Electrical Characteristics (Ta = 25°C)

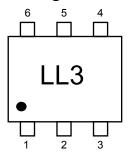
Chara	acteristics	Symbol	Test Condition		Min	Тур.	Max	Unit	
Gate leakage cur	rent	I _{GSS}	$V_{GS}=\pm 10~V,~V_{DS}=0V$			—	±10	μA	
Drain-source bre	akdown voltage	V (BR) DSS	$I_D = 0.1 \text{ mA}, V_{GS} = 0V$		20	_	_	V	
Drain cutoff curre	nt	I _{DSS}	$V_{DS} = 20 V, V_{GS} = 0V$		_	_	1	μA	
Gate threshold vo	oltage	V _{th}	$V_{DS} = 3 V, I_D = 1 mA$		0.4	_	1.0	V	
Forward transfer	admittance	Y _{fs}	$V_{DS} = 3 V, I_{D} = 50 mA$	(Note 2)	115	_	_	mS	
		R _{DS} (ON)	I _D = 50 mA, V _{GS} = 4 V	(Note 2)	_	1.5	3	Ω	
Drain–source ON-resistance	$I_D = 50 \text{ mA}, \text{ V}_{GS} = 2.5 \text{ V}$		(Note 2)	_	2	4			
	$I_D = 5 \text{ mA}, V_{GS} = 1.5 \text{ V}$		(Note 2)	_	3	8			
			$I_D = 5 \text{ mA}, V_{GS} = 1.2 \text{ V}$	(Note 2)	_	5	20		
Input capacitance)	C _{iss}			_	9.5	_		
Reverse transfer capacitance		C _{rss}	$V_{DS} = 3 \text{ V}, \text{ V}_{GS} = 0 \text{ V}, \text{ f} = 1 \text{ MHz}$		_	4.1	_	pF	
Output capacitand	се	C _{oss}	C _{oss}		_	9.5	_	1	
	Turn-on time	t _{on}	V _{DD} = 3 V, I _D = 50 mA,		_	115	_		
Switching time	Turn-off time	t _{off}	$V_{GS} = 0$ to 2.5 V		_	300	_	ns	
Drain-source forward voltage		V _{DSF}	I _D = - 180 mA, V _{GS} = 0V	(Note 2)	_	-0.9	-1.2	V	

Q2 Electrical Characteristics (Ta = 25°C)

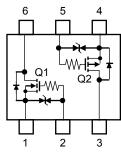
Charac	teristics	Symbol	Test Condition		Min	Тур.	Max	Unit	
Gate leakage curre	ent	I _{GSS}	$V_{GS} = \pm 10 \text{ V}, V_{DS} = 0 \text{ V}$		_	_	±10	μA	
Drain-source breal	kdown voltage	V (BR) DSS	I_{D} = -0.1 mA, V_{GS} = 0 V		-20	_	_	V	
Drain cutoff current	t	I _{DSS}	$V_{DS} = -20 \text{ V}, \text{ V}_{GS} = 0 \text{ V}$		_	_	-1	μA	
Gate threshold volt	age	V _{th}	$V_{DS} = -3 V, I_D = -1 mA$		-0.4	_	-1.0	V	
Forward transfer ad	dmittance	Y _{fs}	$V_{DS} = -3 V, I_D = -50 mA$ (Note 2)		77	-	_	mS	
Drain–source ON-resistance		R _{DS} (ON)	I_{D} = -50 mA, V_{GS} = -4 V	(Note 2)		4.3	8	Ω	
			I _D = -50 mA, V _{GS} = -2.5 V	(Note 2)	_	5.6	11		
			$I_{D} = -5 \text{ mA}, V_{GS} = -1.5 \text{ V}$	(Note 2)	_	8.2	22		
			$I_D = -2 \text{ mA}, V_{GS} = -1.2 \text{ V}$	(Note 2)	_	11	44		
Input capacitance	it capacitance C _{iss}			_	12.2	_			
Reverse transfer capacitance		C _{rss}	V_{DS} = -3 V, V_{GS} = 0 V, f = 1 MHz			6.5	_	pF	
Output capacitance	9	C _{oss}				10.4	_		
Switching time	Turn-on time	t _{on}	V _{DD} = -3 V, I _D = -50 mA, V _{GS} = 0 to -2.5 V		_	175	—		
	Turn-off time	t _{off}			—	251	—	ns	
Drain-source forward voltage		V _{DSF}	$I_D = 100 \text{ mA}, V_{GS} = 0 \text{ V}$	(Note 2)	—	0.83	1.2	V	

Note 2: Pulse test

Marking



Equivalent Circuit (top view)



90%

toff

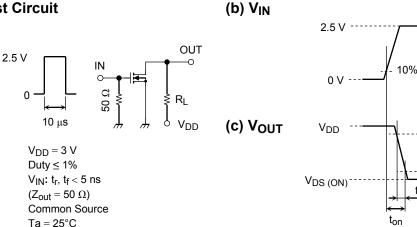
10%

90%

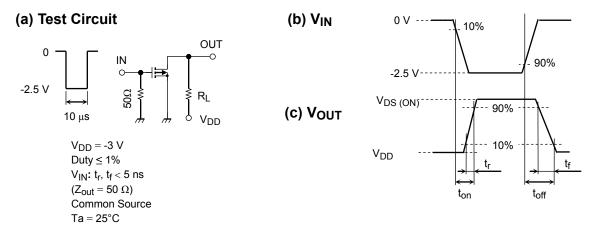
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Q1 Switching Time Test Circuit

(a) Test Circuit



Q2 Switching Time Test Circuit



Q1 Usage Considerations

Let V_{th} be the voltage applied between gate and source that causes the drain current (I_D) to below (1 mA for the Q1 of the SSM6L35FE). Then, for normal switching operation, $V_{GS(on)}$ must be higher than V_{th} , and $V_{GS(off)}$ must be lower than V_{th} . This relationship can be expressed as: $V_{GS(off)} < V_{th} < V_{GS(on)}$. Take this into consideration when using the device.

Q2 Usage Considerations

Let V_{th} be the voltage applied between gate and source that causes the drain current (I_D) to below (-1 mA for the Q2 of the SSM6L35FE). Then, for normal switching operation, $V_{GS(on)}$ must be higher than V_{th} , and $V_{GS(off)}$ must be lower than V_{th} . This relationship can be expressed as: $V_{GS(off)} < V_{th} < V_{GS(on)}$.

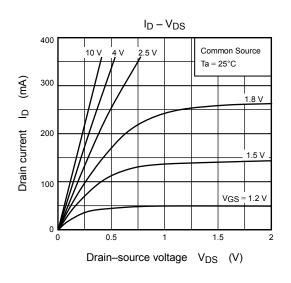
Take this into consideration when using the device.

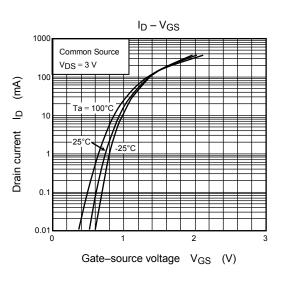
Handling Precaution

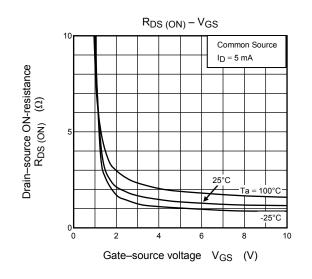
When handling individual devices that are not yet mounted on a circuit board, make sure that the environment is protected against electrostatic discharge. Operators should wear antistatic clothing, and containers and other objects that come into direct contact with devices should be made of antistatic materials.

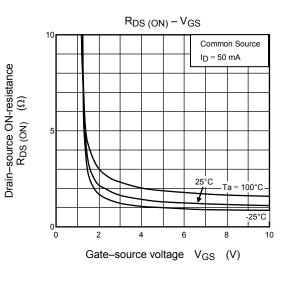
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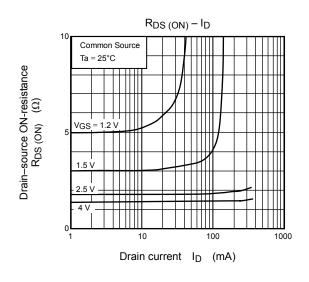
Q1 (N-ch MOSFET)

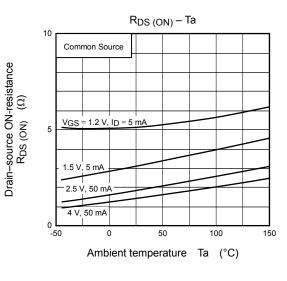






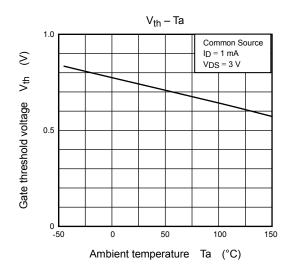


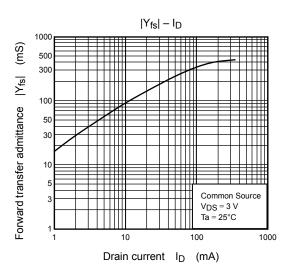


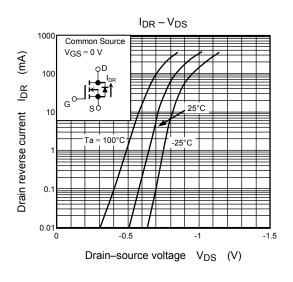


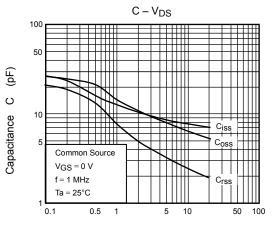
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Q1 (N-ch MOSFET)

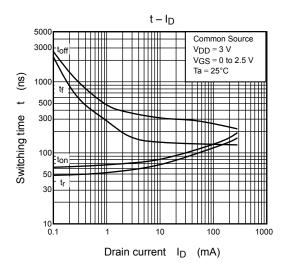




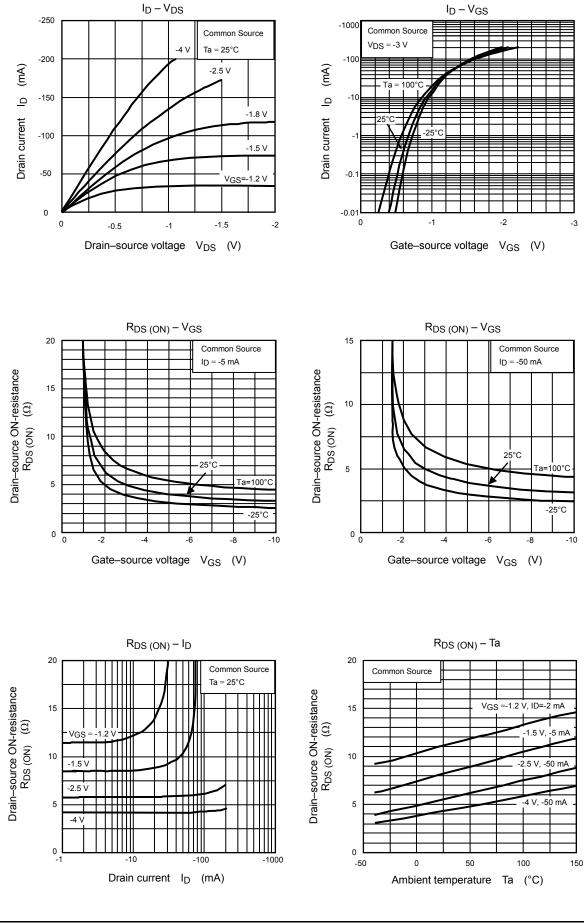




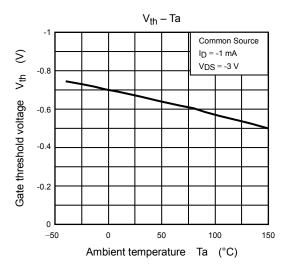


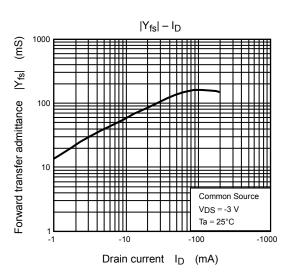


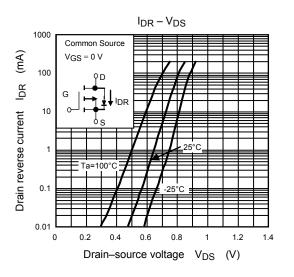
Q2 (P-ch MOSFET)

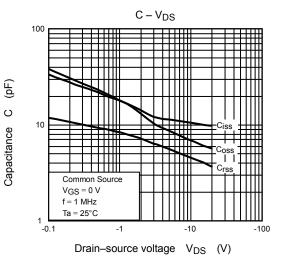


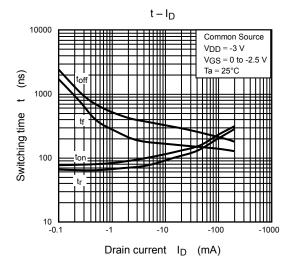
Q2 (P-ch MOSFET)



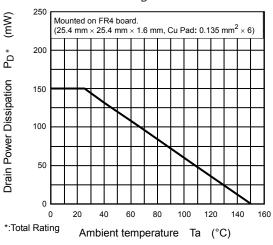








P_D *– Ta



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